

PATENT ASSIGNMENT

Electronic Version v1.1

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SUBMISSION TYPE:

NEW ASSIGNMENT

NATURE OF CONVEYANCE:

ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Tomohiro Uno	12/21/2009
Keiichi Kimura	12/21/2009
Takashi Yamada	12/21/2009

RECEIVING PARTY DATA

Name:	NIPPON STEEL MATERIALS CO., LTD.
Street Address:	14-1, Sotokanda 4-chome, Chiyoda-ku
City:	Tokyo
State/Country:	JAPAN
Postal Code:	1010021

Name:	NIPPON MICROMETAL CORPORATION
Street Address:	158-1, Oaza Sayamagahara, Iruma-shi
City:	Saitama
State/Country:	JAPAN
Postal Code:	3580032

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12669662

CORRESPONDENCE DATA

Fax Number: (212)527-7701

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CH \$40.00 12669662

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PATENT
REEL: 023846 FRAME: 0753

ATTORNEY DOCKET NUMBER:	09864/0213424-US0
NAME OF SUBMITTER:	Junko Harada
Total Attachments: 2 source=Assignments#page1.tif source=Assignments#page2.tif	

ASSIGNMENT

For value received, I/we Tomohiro UNO, Keiichi KIMURA,
and Takashi YAMADA
residing respectively at Tokyo, Japan; Tokyo, Japan; Saitama, Japan

hereby sell, assign, and transfer to NIPPON STEEL MATERIALS CO., LTD.;
NIPPON MICROMETAL CORPORATION
corporations existing under the laws of Japan
located at 14-1, Sotokanda 4-chome, Chiyoda-ku, Tokyo 1010021, Japan;
158-1, Oaza Sayamagahara, Iruma-shi, Saitama 3580032, Japan
and its successors, assigns, and legal representatives, the entire right, title, and interest for
all countries including the United States of America, in and to certain inventions relating to
BONDING WIRE FOR SEMICONDUCTOR DEVICES

described in an application for Letters Patent of the United States, executed by me/us on this
date, and all patents which may be granted therefor, and all divisions, reissues, continuations
and extensions thereof, and authorize and request the Commissioner of Patents and
Trademarks to issue all patents on said improvements or resulting therefrom to said
Company as assignee of the entire interest, and covenant that I/we have full right so to do,
and agree that I/we will communicate to said Company or its representatives any facts
known to me/us respecting said improvements and testify in any legal proceedings, sign all
lawful papers, execute all divisional, continuing and reissue applications, make all rightful
oaths and generally do everything possible to aid said Company, its successors, assigns, and
nominees, to obtain and enforce proper protection for said invention in the United States.

Signature Tomohiro UNO
Tomohiro UNO

Date December 21, 2009

Signature Keiichi KIMURA
Keiichi KIMURA

Date December 21, 2009

Signature _____
Takashi YAMADA

Date _____

Signature _____

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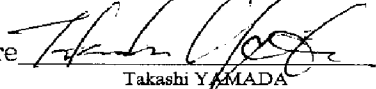
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Trademarks to issue all patents on said improvements or resulting therefrom to said
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and agree that I/we will communicate to said Company or its representatives any facts
known to me/us respecting said improvements and testify in any legal proceedings, sign all
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oaths and generally do everything possible to aid said Company, its successors, assigns, and
nominees, to obtain and enforce proper protection for said invention in the United States.

Signature _____
Tomohiro UNO

Date _____

Signature _____
Keiichi KIMURA

Date _____

Signature 
Takashi YAMADA

Date December 21, 2009

Signature _____

Date _____

Signature _____

Date _____

Signature _____

Date _____